Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	5 X 5 X 0.75 (3.3 EP)
Lead Count	32
Terminal Finish	100 Sn
MS Number	MS010602C

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.31E-02	86.91	869100	38.44	384398
Thermosets	Epoxy & Phenol Resin	Proprietary	3.40E-03	12.78	127800	5.65	56525
Other inorganic materials	Carbon black	1333-86-4	8.24E-05	0.31	3100	0.14	1371
Subtotal			2.66 E-02	100.00	1000000	44.23	442294

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.82 E-02	97.50	975000	46.89	468896
Copper & its alloys	Iron	7439-89-6	6.79 E-04	2.35	23500	1.13	11302
Copper & its alloys	Zinc	7440-66-6	3.47 E-05	0.12	1200	0.06	577
Copper & its alloys	Phosphorus	7723-14-0	8.67 E-06	0.03	300	0.01	144
Subtotal			2.89 E-02	100.00	1000000	48.09	480919

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.89 E-04	100.0	1000000	0.48	4809

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.69 E-03	100.0	1000000	2.81	28061

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.18 E-04	99.0	990000	0.53	5298
Precious metals	Palladium	7440-05-3	3.22 E-06	1.0	10000	0.01	54
Subtotal			3.22 E-04	100.0	1000000	0.54	5352

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.03 E-03	100.0	1000000	3.38	33823

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.19 E-04	77.00	770000	0.37	3651
Other organic materials	Acrylic resin	Proprietary	1.99 E-05	7.00	70000	0.03	332
Other organic materials	Acrylate	Proprietary	1.57 E-05	5.50	55000	0.03	261
Other organic materials	Polybutadiene derivative	Proprietary	1.28 E-05	4.50	45000	0.02	213
Thermoset	Epoxy resin	Proprietary	7.12 E-06	2.50	25000	0.01	119
Other organic materials	Butadiene Copolymer	Proprietary	4.27 E-06	1.50	15000	0.01	71
Others	Additive	Proprietary	4.27 E-06	1.50	15000	0.01	71
Others	Peroxide	Proprietary	1.42 E-06	0.50	5000	0.002	24
Subtotal			2.85 E-04	100.0	1000000	0.47	4741

	Weight (g)	Percentage (%)	PPM
Package Totals	**6.01 E-02**	100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
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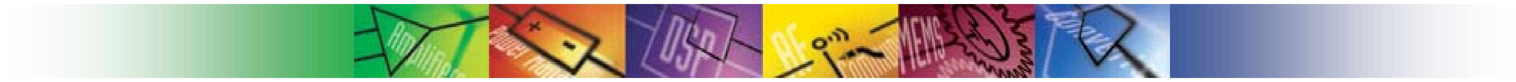

Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	5 X 5 X 0.75 (3.3 EP)
Lead Count	32
Terminal Finish	NiPdAu
MS Number	MS011047B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.95E-02	86.91	869100	49.16	491616
Thermosets	Epoxy & Phenol Resin	Proprietary	4.34E-03	12.78	127800	7.23	72292
Other inorganic materials	Carbon black	1333-86-4	1.05E-04	0.31	3100	0.18	1754
Subtotal			3.40E-02	100.00	1000000	56.57	565661

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.34 E-02	97.50	975000	38.89	388942
Copper & its alloys	Iron	7439-89-6	5.63 E-04	2.35	23500	0.94	9375
Copper & its alloys	Zinc	7440-66-6	2.88 E-05	0.12	1200	0.05	479
Copper & its alloys	Phosphorus	7723-14-0	7.19 E-06	0.03	300	0.01	120
Subtotal			2.40 E-02	100.00	1000000	39.89	398915

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	5.79 E-04	97.3	973000	0.96	9626
Precious metals	Palladium	7440-05-3	1.31 E-05	2.2	22000	0.02	218
Precious metals	Gold	7440-57-5	2.97 E-06	0.5	5000	0.00	49
Subtotal			5.95 E-04	100.00	1000000	0.99	9893

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.27 E-04	99.0	990000	0.21	2106
Precious metals	Palladium	7440-05-3	1.28 E-06	1.0	10000	0.002	21
Subtotal			1.28 E-04	100.0	1000000	0.21	2128

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.05 E-03	100.0	1000000	1.76	17552

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.95 E-04	84.00	840000	0.49	4915
Other organic materials	Epoxy Resin	9003-36-5 / 30583-72-3	4.22 E-05	12.00	120000	0.07	702
Other organic materials	t-butyl phenyl glycidyl ether	3101-60-8	7.03 E-06	2.00	20000	0.01	117
Other organic materials	Phenolic hardener	92-88-6 / 26834-02-6	5.27 E-06	1.50	15000	0.01	88
Other organic materials	Butyl cellosolve acetate	112-07-2	1.76 E-06	0.50	5000	0.003	29
Subtotal			3.52 E-04	100.0	1000000	0.59	5851

	Weight (g)	Percentage (%)	PPM
Package Totals	**6.01 E-02**	**100.00**	**1000000**

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